

PROCEEDINGS OF SPIE

***Photonics Packaging, Integration,
and Interconnects IX***

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Ray T. Chen**
Editors

**26-28 January 2009
San Jose, California, United States**

Volume 7221

Proceedings of SPIE, 0277-786X, v. 7221

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Author(s), "Title of Paper," in *Photonics Packaging, Integration, and Interconnects IX*, edited by Alexei L. Glebov, Ray T. Chen, Proceedings of SPIE Vol. 7221 (SPIE, Bellingham, WA, 2009) Article CID Number.

ISSN 0277-786X
ISBN 9780819474674

Published by

SPIE

P.O. Box 10, Bellingham, Washington 98227-0010 USA
Telephone +1 360 676 3290 (Pacific Time) · Fax +1 360 647 1445
SPIE.org

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